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ABSTRACT

[Abstract]

[Problem] To provide a sputtering target structure which has good machinability and thermal conductivity and has good wettability with soldering materials, which is inexpensive and can be used repeatedly for a long period of time, and which is free from problems of cracking and peeling of the sputtering target therein.

[Means for Solution] A sputtering target structure formed by bonding a sputtering target and a backing plate, wherein the backing plate is formed of a material that has the difference in the linear expansion coefficient between it and the sputtering target material of at most $2 \times 10^{-6}/K$, and a copper plate having a thickness of from 0.3 to 1.5 mm is disposed on at least one face of the backing plate.

[Selected Drawing] Fig. 1.